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(54) **POWER CONVERSION DEVICE**

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(57) **ABSTRACT**

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The power conversion device has a case, a semiconductor module, a first cooler that cools the semiconductor module from one side, a second cooler that cools the semiconductor module from the back side, and a coupling pipe that couples a flow path of the first cooler with a flow path of the second cooler. A flow rate of the refrigerant is made different between the flow paths, and the flow path having a larger flow rate is larger in cross-sectional area than the flow path having a smaller flow rate. The first cooler having a wider flow path is formed by a part of the case that houses the semiconductor module, and the second cooler having a narrower flow path is housed in the case together with the semiconductor module.

